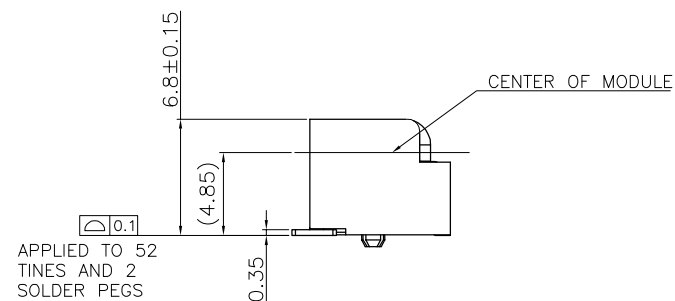
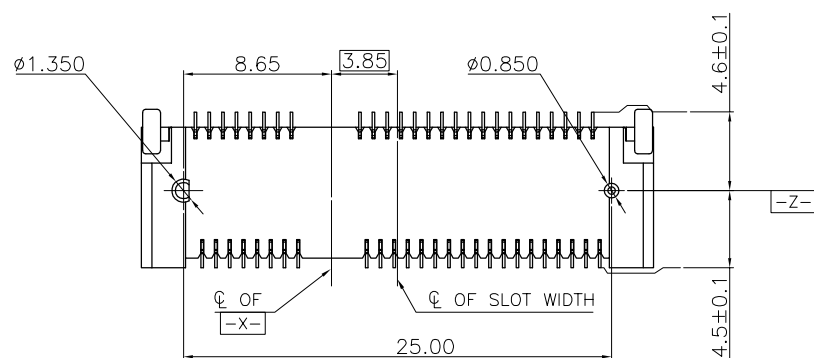
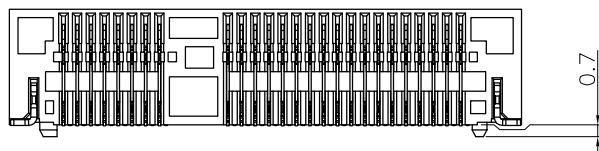
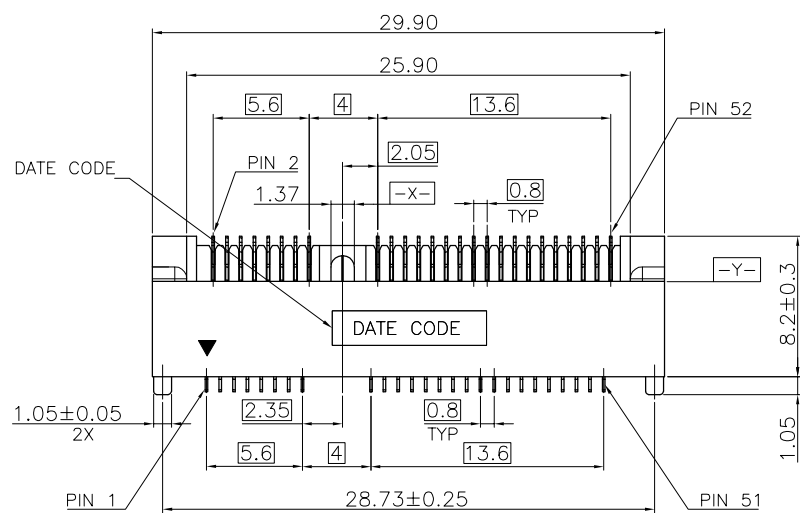


[illegible]

NOTES:

1. MATERIAL:

HOUSING: HIGH TEMPERATURE PLASTIC, UL94 V-0, BLACK COLOR,

CONTACTS: COPPER ALLOY

PEGS: COPPER ALLOY

2. FINISH:

CONTACTS: SELECTED GOLD PLATING ON THE CONTACT AREA,

1u" GOLD PLATING ON THE SOLDER TAILS,

50u" NICKEL UNDERPLATING OVER ALL.

PEGS: 120u" MATTE-TIN OVER 50u" . NICKEL.

3. CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALLIZATION.

4. EDGE BEVEL MUST BE PRESENT AND FREE OF CUTTING BURRS FROM PCB AND CONTACT MATERIALS.

5. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR

10 SECONDS IN RE-FLOW APPLICATION.

6. PRODUCT SPECIFICATION: GS-12-1513

PRODUCT NUMBER CODE

10152143- 052 R X LF

52 CONTACTS

PACKING OPTIONS
R: TAPE & REEL

LEAD FREE

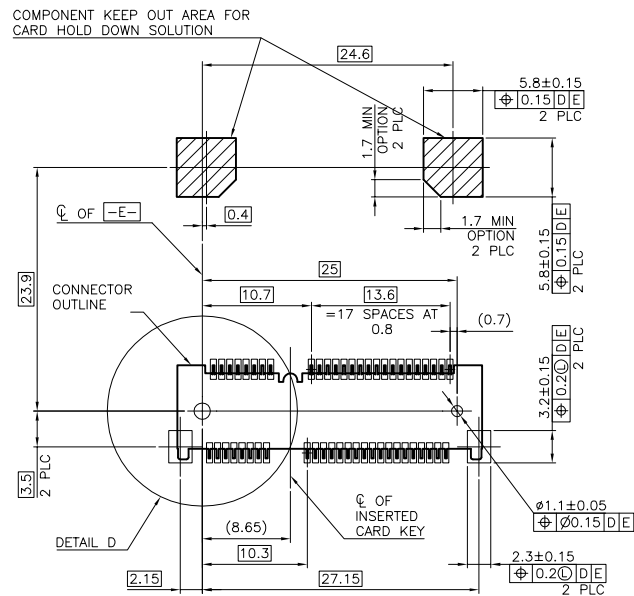
CONTACT AREA PLATING

0: 30u" GOLD

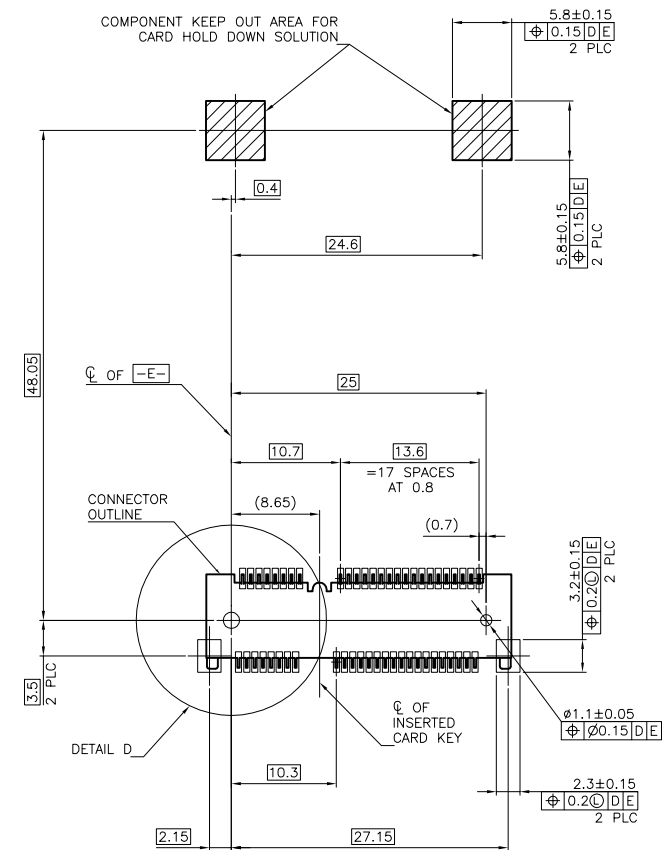
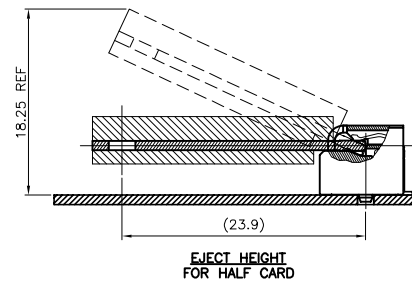
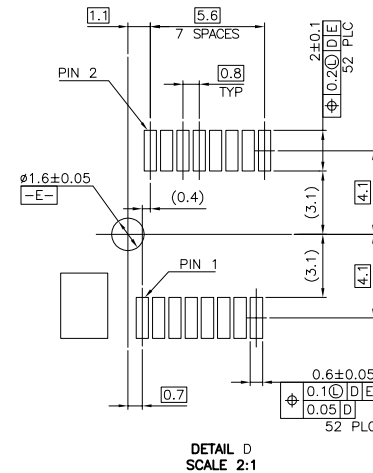
1: 10u" GOLD

2: GOLD FLASH

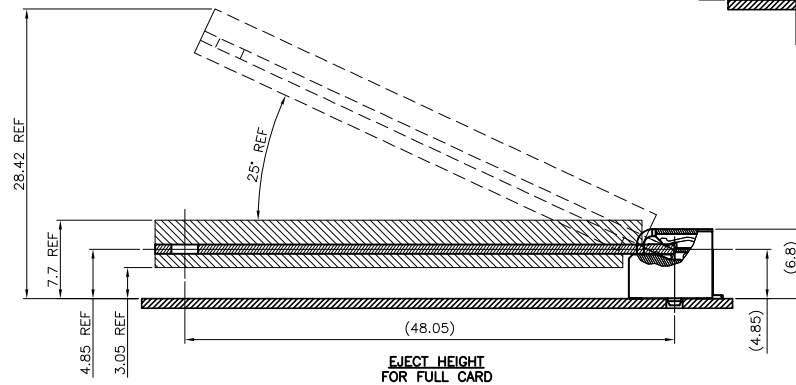
mat'l. code -				surface -	tolerance ASME_Y14.5	projection 	product family PCI_EXPRESS			
lfr	ecn no	dr	date	tolerances unless otherwise specified			title			
				angles	.0±0.30	MM	MINI_PCI_EXPRESS 6.8MM_HEIGHT			
				±2'	.00±0.20 .000±0.10	scale N/A				
				dr	WINSTON_ZHU 2020-05-12	Amphenol FCI	dwg no		sheet 2 of 5	size
				engr	ZHENHUA_LIU 2020-05-12		10152143			A4
				chr			type		CUSTOMER Drawing	
				appd	HEAVEN_CEN 2020-05-12					
sheet index	revision sheet	A								

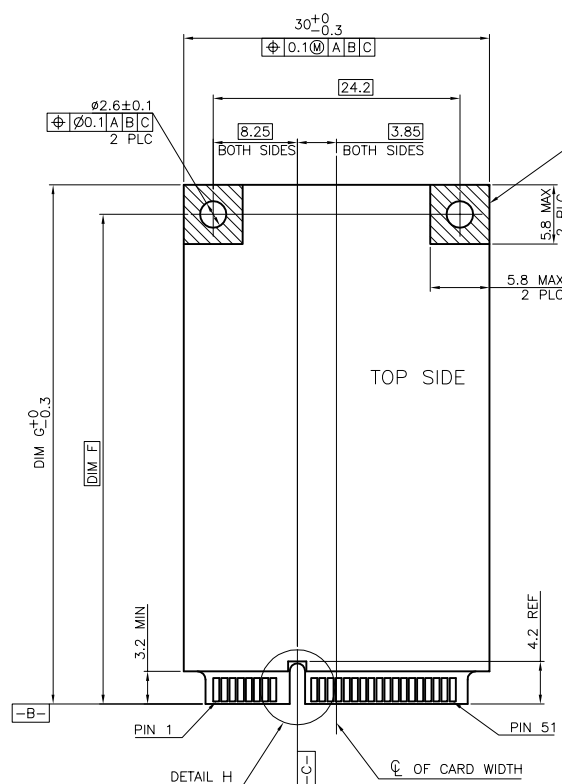


RECOMMENDED P.C. BOARD PATTERN LAYOUT
FOR HALF CARD CONNECTOR
(TOP VIEW)

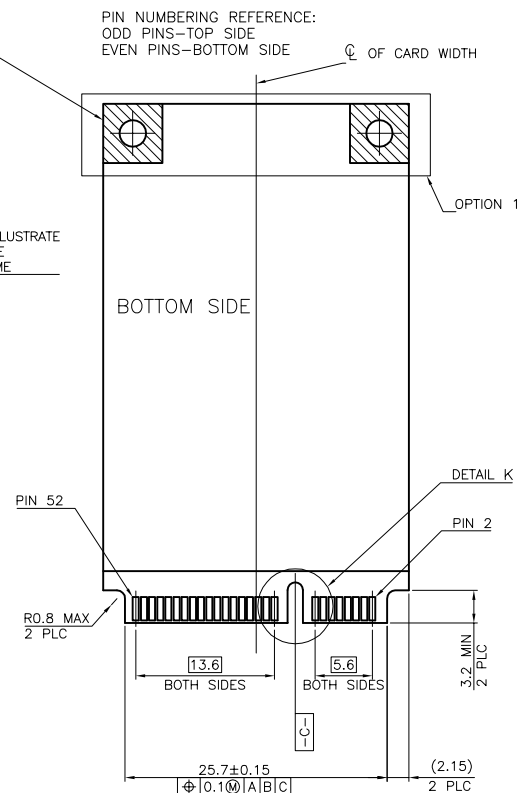
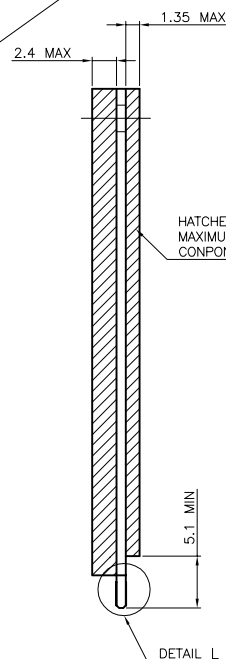


RECOMMENDED P.C. BOARD PATTERN LAYOUT
FOR FULL CARD CONNECTOR
(TOP VIEW)

[illegible]

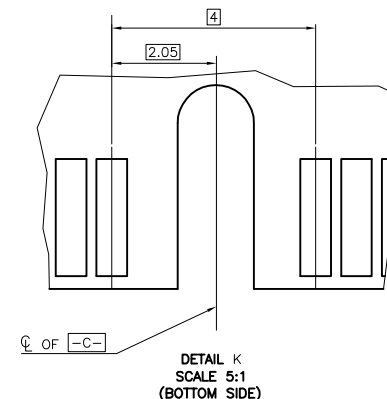
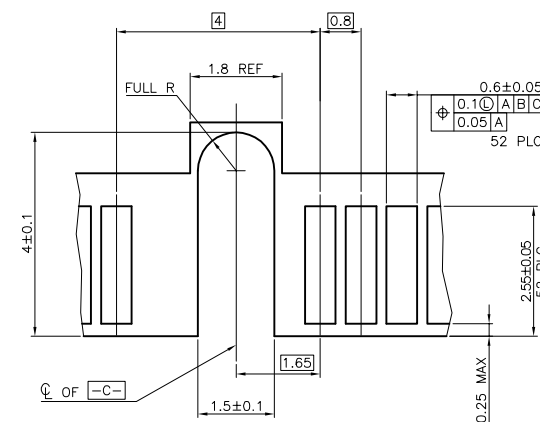


COMPONENT AND ROUTING (ALL LAYERS)
KEEP OUT AREA FOR HOLD DOWN SOLUTIONS



DIM F	DIM G
48.05	50.95
23.9	26.8

FULL-MINI CARD
HALF-MINI CARD



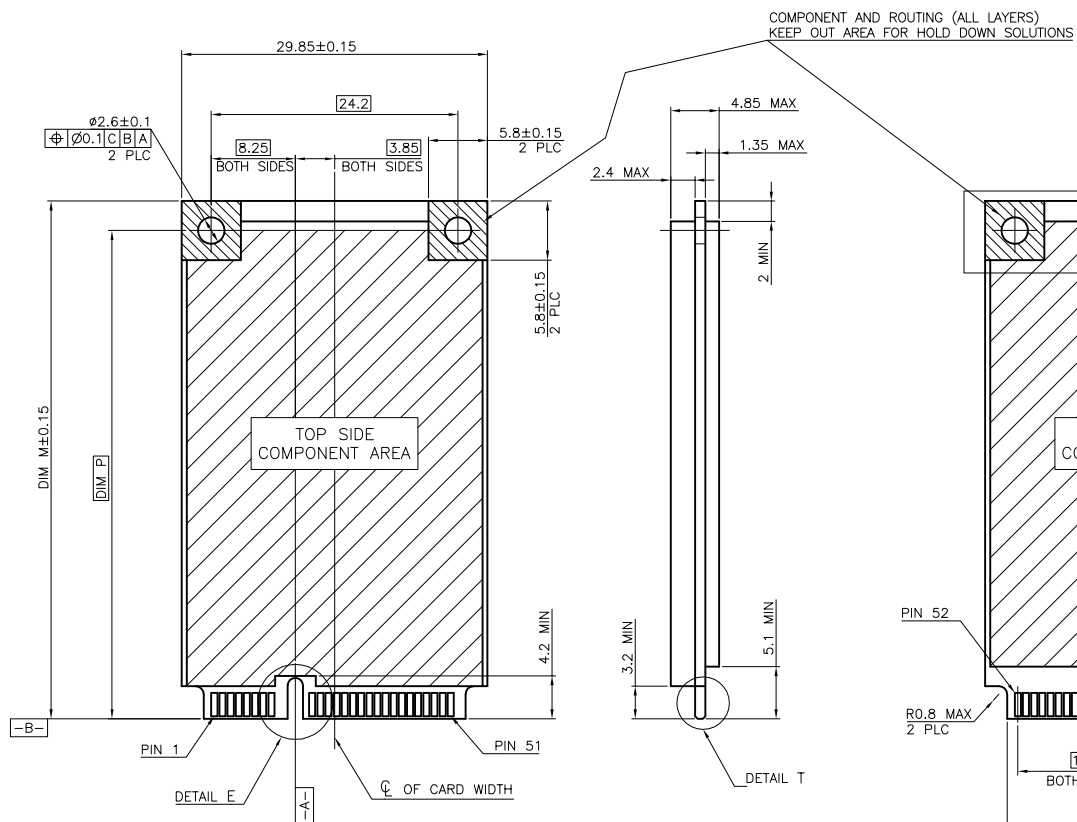
NOTES:

⚠ CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES
PLATING AND/OR METALLIZATION.

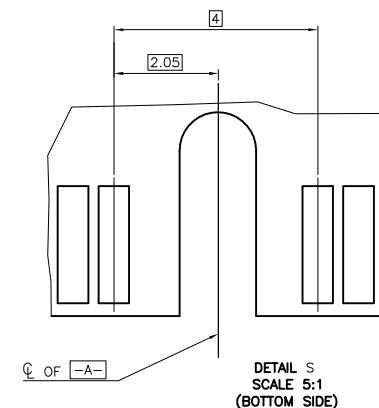
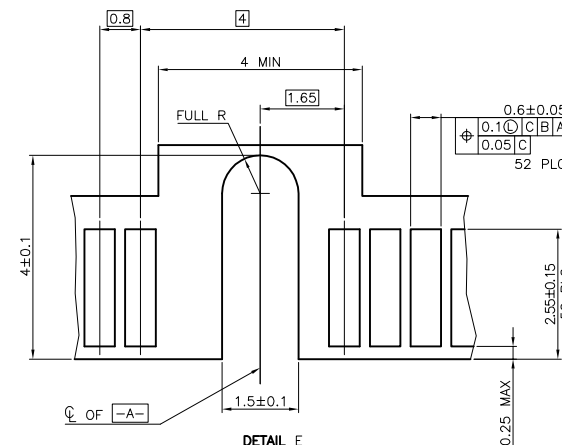
⚠ EDGE BEVEL MUST BE PRESENT AND FREE OF CUTTING
BURRS FROM PCB AND CONTACT MATERIALS.

FOR PCI EXPRESS MINI CARD

mat'l. code	-	surface	✓ ASME_Y14.5	tolerance	ASME_Y14.5	projection	product family	PCI_EXPRESS
lfr	ecn no	dr	date	tolerances unless otherwise specified		MM	title	MINI_PCIE
18				angles	Line 0.2±0.30 0.00±0.20 ±2' .000±0.10	scale N/A	8.6MM_HEIGHT	
		dr	WINSTON_ZHU	2020-05-12			dwg no	10152143
		engr	ZHENHUA_LIU	2020-05-12			sheet 4 of 5	A4
		chr					size	
		app	HEAVEN_CEN	2020-05-12			type	CUSTOMER Drawing
sheet	revision	A						
index	sheet							



DIM P	DIM M	
48.05	50.8	FULL CARD
23.9	26.8	HALF CARD



NOTES:

- △ CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALLIZATION.
- △ EDGE BEVEL MUST BE PRESENT AND FREE OF CUTTING BURRS FROM PCB AND CONTACT MATERIALS.
- △ COMPONENT AND ROUTING (TOP/BOTTOM LAYER) KEEP OUT AREA FOR HOLD DOWN SOLUTIONS.

FOR mSATA

mat'l. code	-	surface	✓	tolerance	ASME_Y14.5	projection	product family	PCI_EXPRESS
lfr	ecn no	dr	date	tolerances unless otherwise specified		MM	title	
18				angles	.0±0.30		MINI_PCIE	
				±2'	.00±0.20		6.8MM_HEIGHT	
					.000±0.10	scale N/A		
		dr	WINSTON_ZHU	2020-05-12			dwg no	sheet 5 of 5 size
		engr	ZHENHUA_LIU	2020-05-12			10152143	A4
		chr						
		appd	HEAVEN_CEN	2020-05-12			type	CUSTOMER Drawing
sheet index	revision	A						